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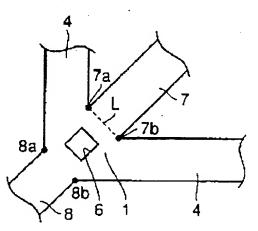
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## 54) SEMICONDUCTOR DEVICE

## 57)Abstract:

ROBLEM TO BE SOLVED: To provide a semiconductor device aving a resin peeling prevention hole and provided with a lead frame ifficult to concentrate deformation in the neighborhood thereof.
OLUTION: The resin peeling prevention hole 5 is provided on the itersection part 1 of a reinforcing frame 4 and an inside hanging lead in the lead frame, and positioned on the intersection part of the area of the contrary side of a die pad rather than a line L connecting first and second inside hanging lead root boundary points 7a, 7b being a coint in which the reinforcing frame continues to both the side parts of a inside hanging lead extending from the intersection part.



## **EGAL STATUS**

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